L Number	Hits	Search Text	DB	Time stamp
3	324	(border\$1less with contact) and (stop or	USPAT	2004/09/16
		stopped or stopping or etch\$1stop or		11:31
4	206	(etch adj stop))		2004/00/16
4	206	((border\$1less with contact) and (stop or stopped or stopping or etch\$1stop or	USPAT	2004/09/16
		(etch adj stop))) and @ay<=1999		10.47
5	206	(((border\$lless with contact) and (stop	USPAT	2004/09/16
		or stopped or stopping or etch\$1stop or		10:49
		(etch adj stop))) and @ay<=1999) and		
6	32	contact ("4318751" "4446476" "4519128"	USPAT	2004/09/16
]	"4534824" "4549927" "4656497"	USPAI	10:56
		"4733287" "4797373" "4808555"		
		"4824793" "4876217" "4884123"		
		"4939567" "4945069" "5003375"		
		"5015594" "5064777" "5100823" "5106777" "5108938" "5112772"		
		"5268330" "5275965" "5315142"		
		"5362678" "5389559" "5395786"		
		"5422294" "5457339" "5460987"		
7	5	"5482869" "5488010").PN. ("5316965" "5804862" "5880006"	USPAT	2004/09/16
'		"5902127" "6051472").PN.	OSPAI	2004/09/16
8	2	("5759867" "5935875").PN.	USPAT	2004/09/16
	4.0			11:09
9	13	5840624.URPN.	USPAT	2004/09/16
10	458	border\$11ess with contact	USPAT	11:21 2004/09/16
		Word of the state	OSIAI	11:23
11	293	(border\$11ess with contact) and @ay<=1999	USPAT	2004/09/16
12	87	//handan011annanith		11:24
12	07	((border\$1less with contact) and @ay<=1999) not ((((border\$1less with	USPAT	2004/09/16
		contact) and (stop or stopped or stopping		11.24
		or etch\$1stop or (etch adj stop))) and		
13	70050	@ay<=1999) and contact)		
13	72358	<pre>(stop or stopped or stopping or etch\$1stop or (etch adj stop)) with</pre>	USPAT	2004/09/16
		(composite or two)		11:4/
14	1076	<pre>(etch\$1stop\$4 or (etch\$3 adj stop\$4))</pre>	USPAT	2004/09/16
1.5	000	with (composite or two)		11:32
15	993	<pre>((etch\$1stop\$4 or (etch\$3 adj stop\$4)) with (composite or two)) and</pre>	USPAT	2004/09/16
		semiconductor		11:32
16	855	(((etch\$1stop\$4 or (etch\$3 adj stop\$4))	USPAT	2004/09/16
		with (composite or two)) and		11:32
17	567	<pre>semiconductor) and contact ((((etch\$1stop\$4 or (etch\$3 adj stop\$4))</pre>	IICDAM	2004/00/16
• '	307	with (composite or two)) and	USPAT	2004/09/16 11:33
		semiconductor) and contact) and @ay<=1999		*****
18	253	(((((etch\$1stop\$4 or (etch\$3 adj stop\$4))	USPAT	2004/09/16
		with (composite or two)) and semiconductor) and contact) and		11:35
		@ay<=1999) and ((etch\$1stop\$4 or (etch\$3		
		adj stop\$4)) with (nitride or oxynitride		
		or SiON or SiN or "Si.sub.3 N.sub.4"))		
19	57	((((((etch\$1stop\$4 or (etch\$3 adj stop\$4)) with (composite or two)) and	USPAT	2004/09/16
[semiconductor) and contact) and		11:55
		@ay<=1999) and ((etch\$1stop\$4 or (etch\$3		
		adj stop\$4)) with (nitride or oxynitride		
		or SiON or SiN or "Si.sub.3 N.sub.4")))		
		and ((stop or stopped or stopping or etch\$1stop or (etch adj stop)) with		
		composite)		

20	16	("3536547" "3926715" "4430153" "4440729" "4539392" "4600934" "4648179" "4671850" "4784721" "5055907" "5201987" "5229916" "5308442" "5369299" "5376586" "5670062").PN.	USPAT	2004/09/16 11:54
21	72	composite near4 etch\$3 near4 stop	USPAT	2004/09/16 15:05
22	42	(composite near4 etch\$3 near4 stop) and @ay<=1999	USPAT	2004/09/16
23	0	Qiao-Jiamin.in.	USPAT	2004/09/16
24	0	Tzur-Mira-Ben.in.	USPAT	2004/09/16
25	0	Gopalan-Prbhuram.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/16 12:20
26	0	Qiao-Jiamin.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/16 14:09
27	4003	(interconnect or interconnection) same (contact adj hole)	USPAT	2004/09/16
28	793	((interconnect or interconnection) same (contact adj hole)) and ((etch adj stop) or etch\$1stop or stopping or stopped)	USPAT	2004/09/16 14:10
29	502	(((interconnect or interconnection) same (contact adj hole)) and ((etch adj stop) or etch\$1stop or stopping or stopped)) and @ay<=1999	USPAT	2004/09/16 14:10
30	229	((((interconnect or interconnection) same (contact adj hole)) and ((etch adj stop) or etch\$1stop or stopping or stopped)) and @ay<=1999) and (polish or polishing or cmp or planariziation or planarize)	USPAT	2004/09/16 14:11
31	15	<pre>(((((interconnect or interconnection) same (contact adj hole)) and ((etch adj stop) or etch\$1stop or stopping or stopped)) and @ay<=1999) and (polish or polishing or cmp or planariziation or planarize)) and border\$1less</pre>	USPAT	2004/09/16 14:37
32	40	<pre>border\$1less and (((silicon adj oxide) or SiO) with ((silicon adj dioxide) or SiO?sub.2))</pre>	USPAT	2004/09/16 14:38
33	22	(border\$1less and (((silicon adj oxide) or SiO) with ((silicon adj dioxide) or SiO?sub.2))) and @ay<=1999	USPAT	2004/09/16 14:38
34	63	multi\$1layer near4 etch\$3 near4 stop	USPAT	2004/09/16 15:02
35	41	(multi\$1layer near4 etch\$3 near4 stop) and @ay<=1999	USPAT	2004/09/16 15:02
36	84	<pre>(composite\$1 or compositing) near4 etch\$3 near4 stop\$4</pre>	USPAT	2004/09/16 15:05
37	50	((composite\$1 or compositing) near4 etch\$3 near4 stop\$4) and @ay<=1999	USPAT	2004/09/16 15:06
38	8	(((composite\$1 or compositing) near4 etch\$3 near4 stop\$4) and @ay<=1999) not ((composite near4 etch\$3 near4 stop) and @ay<=1999)	USPAT	2004/09/16
39	201	border\$1less and (polishing or polish or cmp) and (etch\$1stop\$3 or (etch\$3 adj stop))	USPAT	2004/09/16 15:50
40	123	(border\$1less and (polishing or polish or cmp) and (etch\$1stop\$3 or (etch\$3 adj stop))) and @ay<=1999	USPAT	2004/09/16 15:50

41	90	((border\$1less and (polishing or polish or cmp) and (etch\$1stop\$3 or (etch\$3 adj stop))) and @ay<=1999) and (doping or	USPAT	2004/09/16 16:07
42	243	<pre>dopant or doped) border\$1less and ((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2))</pre>	USPAT	2004/09/16 16:18
43	196	, ,	USPAT	2004/09/16 16:09
44	131	((border\$1less and ((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2))) and (phosphorous or P!)) and @ay<=1999	USPAT	2004/09/16 16:10
45	60	(border\$1less and ((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2))) and phosphorous	USPAT	2004/09/16 16:09
46	45	((border\$1less and ((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2))) and phosphorous) and @ay<=1999	USPAT	2004/09/16 16:10
47	1620	((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2)) with phosphorous	USPAT	2004/09/16 16:18
48	1338	(((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2)) with phosphorous) and contact	USPAT	2004/09/16 16:18
49	279	((((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2)) with phosphorous) and contact) and (weight or wt)	USPAT	2004/09/16 16:19
50	203	(((((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2)) with phosphorous) and contact) and (weight or wt)) and @ay<=1999	USPAT	2004/09/16 16:19
51	72	(((((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2)) with phosphorous) and contact) and (weight or wt)) and @ay<=1999) and (stop or stopping)	USPAT	2004/09/16 16:34
52	166	PSG with weight	USPAT	2004/09/16
53	42	(PSG with weight) and @ay<=1990	USPAT	2004/09/16 16:34
54	13	5840624.URPN.	USPAT	2004/09/16 16:34
55	128 317	(PSG with weight) and @ay<=1999	USPAT	2004/09/16 16:35
	317	<pre>(border\$1less with contact) and (stop or stopping or etch\$1stop or (etch adj stop))</pre>	USPAT	2004/09/16
	256	((border\$11ess with contact) and (stop or stopping or etch\$1stop or (etch adj stop))) and @ay<=2000	USPAT	2004/09/15 19:00
_	241	(((border\$1less with contact) and (stop or stopping or etch\$1stop or (etch adj stop))) and @ay<=2000) and (nitride or SiN or "Si.sub.3 N.sub.4" or oxy\$1nitride or SiON)	USPAT	2004/09/15 19:02
_	188	((((border\$1less with contact) and (stop or stopping or etch\$1stop or (etch adj stop))) and @ay<=2000) and (nitride or SiN or "Si.sub.3 N.sub.4" or oxy\$1nitride or SiON)) and @ay<=1999	USPAT	2004/09/15 19:24
_	1	6156676.pn.	USPAT	2004/09/15 19:24
_	3	("3742183" "5543365" "5610104").PN.	USPAT	19:24 2004/09/15 19:27